



# Solder paste Delphine 5504HT

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Technical data Delphine 5504HT

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## Halide free solder paste with high melting point

### Description:

**Delphine 5504HT** is a no-clean solder paste with high lead content. It is suitable for applications where a high melting point is needed, like in e.g. component manufacturing.

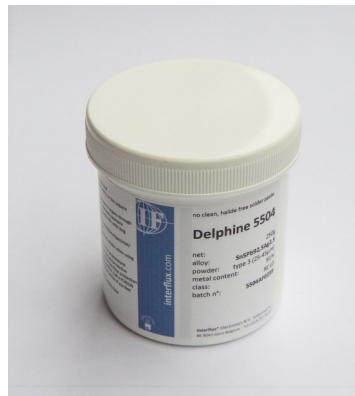
The alloys with high lead content are for some applications exempted from the RoHS guideline and can still be used.

The solder paste has been developed to keep voiding low.

**Delphine 5504HT** is absolutely halide free and therefore it is very reliable and suitable for critical applications.

The paste does not contain colophony resulting in less machine pollution and oven maintenance.

The residues after reflow are clear and easily penetrated by flying probe- and ICT-test pins.



Products pictured may differ from the product delivered

### More information:

Product handling P. 2

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### Key advantages:

- Absolutely halogen free
- Classification to IPC and EN: **RE LO**

## Availability

alloy	metal content	powder size	packaging
Pb92,5Sn5Ag2,5 (+/- 287-296 °C)	printing: 91%	Standard type 3 (25— 45µ)	500g jar 1kg—1,2kg—1,3kg in 12 Oz. cartridge other packages are available upon request
Pb88Sn10Ag2 (+/- 268-299 °C)			



## Handling

### **Storage**

Store the solder paste in the original packaging, tightly sealed at a preferred temperature of 3° to 7°C

### **Handling**

Let the solder paste reach room temperature prior to opening the packaging. Stir well before use.

### **Printing**

Assure good sealing between PCB and stencil. Apply no more than enough squeegee pressure to get a clean stencil. Apply enough solder paste to the stencil to allow smooth rolling during printing. Regular replenish fresh solder paste.

### **Maintenance**

Set an under stencil clean interval which provides continuous printing quality. **IS-C8020** is recommended as cleaning agent in pre saturated wipes and USC liquid.

### **Reuse**

Avoid mixing used and fresh paste. Do not put packages back into refrigeration when already opened.

Store used paste in a closed separate jar at room temperature. A test board before reusing in production is advisable

### **Safety**

Please always consult the safety datasheet of the product.

## Reflow

Because of the high melting point, it is advisable to do the soldering process in a N<sub>2</sub>/H<sub>2</sub> atmosphere.

A peak temperature of at least 10° over melting point is advisable.



## Operating parameter recommendations

Printing  
speed: 20—120 mm/sec  
squeegee pressure:  $\pm 250$ g / cm length  
U.S.C. interval: every 10 boards  
temperature range: 15°C to 25°C

Mounting  
tack time: > 4 hours

I.C.T  
flying probe testable  
pin-bed testable

Trade name : Delphine 5504HT No-Clean Solder Paste

D i s c l a i m e r

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